

Hex D Flip-Flop with Common Clock and Reset

High-Performance Silicon-Gate CMOS

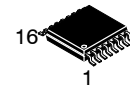
MC74HC174A

The MC74HC174A is identical in pinout to the LS174. The device inputs are compatible with standard CMOS outputs; with pullup resistors, they are compatible with LSTTL outputs.

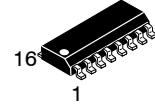
This device consists of six D flip-flops with common Clock and Reset inputs. Each flip-flop is loaded with a low-to-high transition of the Clock input. Reset is asynchronous and active-low.

Features

- Output Drive Capability: 10 LSTTL Loads
- Outputs Directly Interface to CMOS, NMOS, and TTL
- Operating Voltage Range: 2.0 to 6.0 V
- Low Input Current: 1.0 μ A
- In Compliance with the Requirements Defined by JEDEC Standard No. 7 A
- Chip Complexity: 162 FETs or 40.5 Equivalent Gates
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable*
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

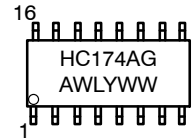
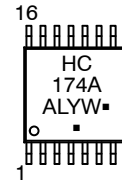


TSSOP-16
DT SUFFIX
CASE 948F



SOIC-16
D SUFFIX
CASE 751B

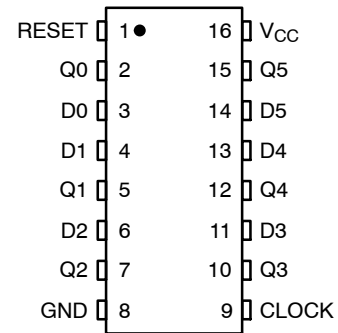
MARKING DIAGRAMS



- A = Assembly Location
- L, WL = Wafer Lot
- Y, YY = Year
- W, WW = Work Week
- G or \blacksquare = Pb-Free Package

(Note: Microdot may be in either location)

PIN ASSIGNMENT



ORDERING INFORMATION

| Device | Package | Shipping [†] |
|-------------------|--------------------|-----------------------|
| MC74HC174ADR2G | SOIC-16 (Pb-Free) | 2500 / Tape & Reel |
| MC74HC174ADTR2G | TSSOP-16 (Pb-Free) | 2500 / Tape & Reel |
| NLV74HC174ADR2G* | SOIC-16 (Pb-Free) | 2500 / Tape & Reel |
| NLV74HC174ADTR2G* | TSSOP-16 (Pb-Free) | 2500 / Tape & Reel |

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

MC74HC174A

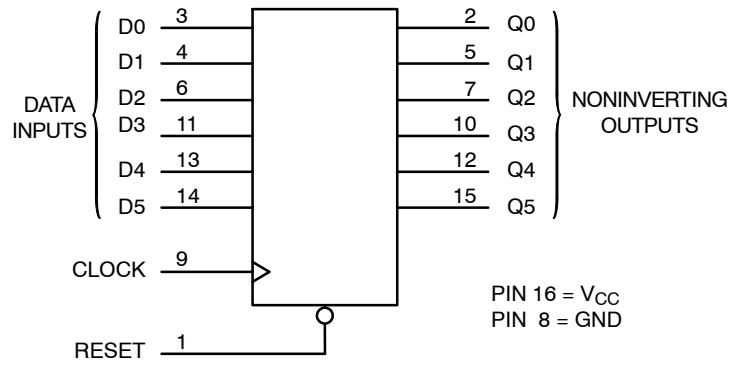


Figure 1. Logic Diagram

FUNCTION TABLE

| Inputs | | | Output |
|--------|-------|---|-----------|
| Reset | Clock | D | Q |
| L | X | X | L |
| H | ↗ | H | H |
| H | ↘ | L | L |
| H | L | X | No Change |
| H | ↖ | X | No Change |

DESIGN/VALUE TABLE

| Design Criteria | Value | Units |
|---------------------------------|--------|-------|
| Internal Gate Count* | 40.5 | ea. |
| Internal Gate Propagation Delay | 1.5 | ns |
| Internal Gate Power Dissipation | 5.0 | μW |
| Speed Power Product | 0.0075 | pJ |

*Equivalent to a two-input NAND gate.

MC74HC174A

MAXIMUM RATINGS

| Symbol | Parameter | Value | Unit |
|---------------|--|--------------------------|---------------|
| V_{CC} | DC Supply Voltage (Referenced to GND) | -0.5 to +7.0 | V |
| V_{IN} | DC Input Voltage (Referenced to GND) | -0.5 to $V_{CC} + 0.5$ | V |
| V_{OUT} | DC Output Voltage (Referenced to GND) (Note 1) | -0.5 to $V_{CC} + 0.5$ | V |
| I_{IN} | DC Input Current, per Pin | ± 20 | mA |
| I_{OUT} | DC Output Current, per Pin | ± 25 | mA |
| I_{CC} | DC Supply Current, V_{CC} and GND Pins | ± 50 | mA |
| T_{STG} | Storage Temperature Range | -65 to +150 | $^{\circ}C$ |
| T_L | Lead Temperature, 1 mm from Case for 10 Seconds SOIC, TSSOP | 260 | $^{\circ}C$ |
| T_J | Junction Temperature Under Bias | +150 | $^{\circ}C$ |
| θ_{JA} | Thermal Resistance SOIC TSSOP | 112 148 | $^{\circ}C/W$ |
| P_D | Power Dissipation in Still Air at 85 $^{\circ}C$ SOIC TSSOP | 500 450 | mW |
| MSL | Moisture Sensitivity | Level 1 | |
| F_R | Flammability Rating Oxygen Index: 30-35% | UL 94 V-0 @ 0.125 in. | |
| V_{ESD} | ESD Withstand Voltage Human Body Model (Note 2) Machine Model (Note 3) Charged Device Model (Note 4) | > 2000 > 100 > 500 | V |
| $I_{LATCHUP}$ | Latchup Performance Above V_{CC} and Below GND at 85 $^{\circ}C$ (Note 5) | ± 300 | mA |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. I_O absolute maximum rating must be observed.
2. Tested to EIA/JESD22-A114-A.
3. Tested to EIA/JESD22-A115-A.
4. Tested to JESD22-C101-A.
5. Tested to EIA/JESD78.

RECOMMENDED OPERATING CONDITIONS

| Symbol | Parameter | Min | Max | Unit |
|-------------------|---|------------------|---------------------------|-------------|
| V_{CC} | DC Supply Voltage (Referenced to GND) | 2.0 | 6.0 | V |
| V_{IN}, V_{OUT} | DC Input Voltage, Output Voltage (Referenced to GND) (Note 6) | 0 | V_{CC} | V |
| T_A | Operating Temperature, All Package Types | -55 | +125 | $^{\circ}C$ |
| t_r, t_f | CLOCK Input Rise and Fall Time (Figure 2) $V_{CC} = 2.0 V$ $V_{CC} = 3.3 V$ $V_{CC} = 4.5 V$ $V_{CC} = 6.0 V$ | 0 0 0 0 | 1000 700 500 400 | ns |

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

6. Unused inputs may not be left open. All inputs must be tied to a high- or low-logic input voltage level.

MC74HC174A

DC ELECTRICAL CHARACTERISTICS (Voltages Referenced to GND)

| Symbol | Parameter | Test Conditions | V _{CC} V | Guaranteed Limit | | | Unit |
|-----------------|--|--|----------------------|------------------|--------|---------|------|
| | | | | -55°C to 25°C | ≤ 85°C | ≤ 125°C | |
| V _{IH} | Minimum High-Level Input Voltage | V _{OUT} = 0.1 V or V _{CC} - 0.1 V I _{OUT} ≤ 20 μA | 2.0 | 1.5 | 1.5 | 1.5 | V |
| | | | 4.5 | 3.15 | 3.15 | 3.15 | |
| | | | 6.0 | 4.2 | 4.2 | 4.2 | |
| V _{IL} | Maximum Low-Level Input Voltage | V _{OUT} = 0.1 V or V _{CC} - 0.1 V I _{OUT} ≤ 20 μA | 2.0 | 0.5 | 0.5 | 0.5 | V |
| | | | 4.5 | 1.35 | 1.35 | 1.35 | |
| | | | 6.0 | 1.8 | 1.8 | 1.8 | |
| V _{OH} | Minimum High-Level Output Voltage | V _{IN} = V _{IH} or V _{IL} I _{OUT} ≤ 20 μA | 2.0 | 1.9 | 1.9 | 1.9 | V |
| | | | 4.5 | 4.4 | 4.4 | 4.4 | |
| | | 6.0 | 5.9 | 5.9 | 5.9 | | |
| | | V _{IN} = V _{IH} or V _{IL} I _{OUT} ≤ 4.0 mA I _{OUT} ≤ 5.2 mA | 4.5 | 3.98 | 3.84 | 3.7 | |
| 6.0 | 5.48 | 5.34 | 5.2 | | | | |
| V _{OL} | Maximum Low-Level Output Voltage | V _{IN} = V _{IH} or V _{IL} I _{OUT} ≤ 20 μA | 2.0 | 0.1 | 0.1 | 0.1 | V |
| | | | 4.5 | 0.1 | 0.1 | 0.1 | |
| | | 6.0 | 0.1 | 0.1 | 0.1 | | |
| | | V _{IN} = V _{IH} or V _{IL} I _{OUT} ≤ 4.0 mA I _{OUT} ≤ 5.2 mA | 4.5 | 0.26 | 0.33 | 0.4 | |
| 6.0 | 0.26 | 0.33 | 0.4 | | | | |
| I _{IN} | Maximum Input Leakage Current | V _{IN} = V _{CC} or GND | 6.0 | ±0.1 | ±1.0 | ±1.0 | μA |
| I _{CC} | Maximum Quiescent Supply Current (per Package) | V _{IN} = V _{CC} or GND I _{OUT} = 0 μA | 6.0 | 4.0 | 40 | 160 | μA |

AC ELECTRICAL CHARACTERISTICS (C_L = 50 pF, Input t_r = t_f = 6.0 ns)

| Symbol | Parameter | V _{CC} V | Guaranteed Limit | | | Unit |
|--------------------------------------|---|----------------------|------------------|--------|---------|------|
| | | | -55°C to 25°C | ≤ 85°C | ≤ 125°C | |
| f _{max} | Maximum Clock Frequency (50% Duty Cycle) (Figures 2 and 5) | 2.0 | 6.0 | 4.8 | 4.0 | MHz |
| | | 4.5 | 30 | 24 | 20 | |
| | | 6.0 | 35 | 28 | 24 | |
| t _{PLH} t _{PHL} | Maximum Propagation Delay, Clock to Q (Figures 3 and 5) | 2.0 | 110 | 140 | 165 | ns |
| | | 4.5 | 22 | 28 | 33 | |
| | | 6.0 | 19 | 24 | 28 | |
| t _{PLH} t _{PHL} | Maximum Propagation Delay, Reset to Q (Figures 2 and 5) | 2.0 | 110 | 140 | 160 | ns |
| | | 4.5 | 21 | 28 | 32 | |
| | | 6.0 | 19 | 24 | 27 | |
| t _{TLH} t _{THL} | Maximum Output Transition Time, Any Output (Figures 2 and 5) | 2.0 | 75 | 95 | 110 | ns |
| | | 4.5 | 15 | 19 | 22 | |
| | | 6.0 | 13 | 16 | 19 | |
| C _{in} | Maximum Input Capacitance | | 10 | 10 | 10 | pF |

| C _{PD} | Power Dissipation Capacitance, per Enabled Output (Note 7) | Typical @ 25°C, V _{CC} = 5.0 V | | | pF |
|-----------------|--|---|--|--|----|
| | | 62 | | | |
| | | | | | |

7. Used to determine the no-load dynamic power consumption: $P_D = C_{PD} V_{CC}^2 f + I_{CC} V_{CC}$.

MC74HC174A

TIMING REQUIREMENTS ($C_L = 50 \text{ pF}$, Input $t_r = t_f = 6.0 \text{ ns}$)

| Symbol | Parameter | Figure | V_{CC} V | Guaranteed Limit | | | | | | Unit |
|------------|--|--------|-------------------|-------------------|--------------------|-------------------|--------------------|-------------------|--------------------|------|
| | | | | -55°C to 25°C | | ≤ 85°C | | ≤ 125°C | | |
| | | | | Min | Max | Min | Max | Min | Max | |
| t_{su} | Minimum Setup Time, Data to Clock | 4 | 2.0 4.5 6.0 | 50 10 9.0 | | 65 13 11 | | 75 15 13 | | ns |
| t_h | Minimum Hold Time, Clock to Data | 4 | 2.0 4.5 6.0 | 5.0 5.0 5.0 | | 5.0 5.0 5.0 | | 5.0 5.0 5.0 | | ns |
| t_{rec} | Minimum Recovery Time, Reset Inactive to Clock | 3 | 2.0 4.5 6.0 | 5.0 5.0 5.0 | | 5.0 5.0 5.0 | | 5.0 5.0 5.0 | | ns |
| t_w | Minimum Pulse Width, Clock | 2 | 2.0 4.5 6.0 | 75 15 13 | | 95 19 16 | | 110 22 19 | | ns |
| t_w | Minimum Pulse Width, Reset | 3 | 2.0 4.5 6.0 | 75 15 13 | | 95 19 16 | | 110 22 19 | | ns |
| t_r, t_f | Maximum Input Rise and Fall Times | 2 | 2.0 4.5 6.0 | | 1000 500 400 | | 1000 500 400 | | 1000 500 400 | ns |

SWITCHING WAVEFORMS AND TEST CIRCUIT

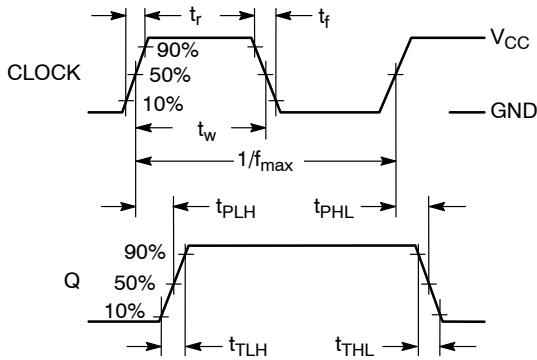


Figure 2. Switching Waveform

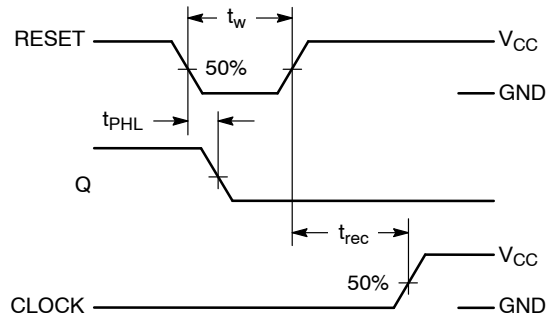


Figure 3. Switching Waveform

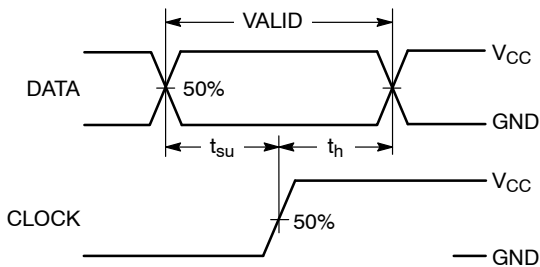
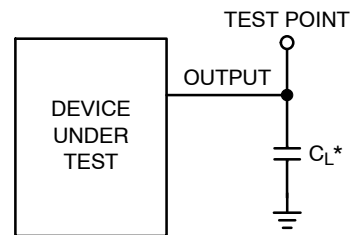


Figure 4. Switching Waveform



*Includes all probe and jig capacitance

Figure 5. Test Circuit

MC74HC174A

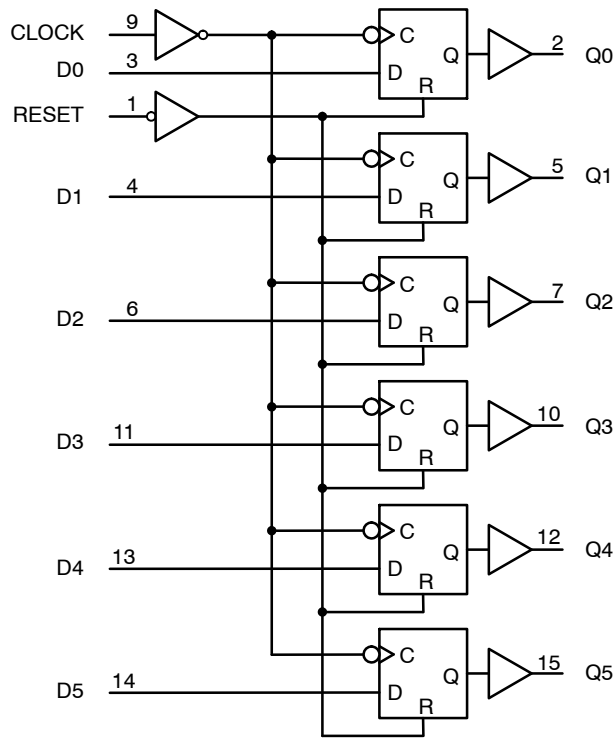


Figure 6. Expanded Logic Diagram

MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

ON Semiconductor®



SCALE 1:1

SOIC-16 CASE 751B-05 ISSUE K

DATE 29 DEC 2006



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

| DIM | MILLIMETERS | | INCHES | |
|-----|-------------|-------|-----------|-------|
| | MIN | MAX | MIN | MAX |
| A | 9.80 | 10.00 | 0.386 | 0.393 |
| B | 3.80 | 4.00 | 0.150 | 0.157 |
| C | 1.35 | 1.75 | 0.054 | 0.068 |
| D | 0.35 | 0.49 | 0.014 | 0.019 |
| F | 0.40 | 1.25 | 0.016 | 0.049 |
| G | 1.27 BSC | | 0.050 BSC | |
| J | 0.19 | 0.25 | 0.008 | 0.009 |
| K | 0.10 | 0.25 | 0.004 | 0.009 |
| M | 0° | 7° | 0° | 7° |
| P | 5.80 | 6.20 | 0.229 | 0.244 |
| R | 0.25 | 0.50 | 0.010 | 0.019 |

- | | | | |
|--|--|--|--|
| <p>STYLE 1:</p> <p>PIN 1. COLLECTOR</p> <p>2. BASE</p> <p>3. EMITTER</p> <p>4. NO CONNECTION</p> <p>5. EMITTER</p> <p>6. BASE</p> <p>7. COLLECTOR</p> <p>8. COLLECTOR</p> <p>9. BASE</p> <p>10. EMITTER</p> <p>11. NO CONNECTION</p> <p>12. EMITTER</p> <p>13. BASE</p> <p>14. COLLECTOR</p> <p>15. EMITTER</p> <p>16. COLLECTOR</p> | <p>STYLE 2:</p> <p>PIN 1. CATHODE</p> <p>2. ANODE</p> <p>3. NO CONNECTION</p> <p>4. CATHODE</p> <p>5. CATHODE</p> <p>6. NO CONNECTION</p> <p>7. ANODE</p> <p>8. CATHODE</p> <p>9. CATHODE</p> <p>10. ANODE</p> <p>11. NO CONNECTION</p> <p>12. CATHODE</p> <p>13. CATHODE</p> <p>14. NO CONNECTION</p> <p>15. ANODE</p> <p>16. CATHODE</p> | <p>STYLE 3:</p> <p>PIN 1. COLLECTOR, DYE #1</p> <p>2. BASE, #1</p> <p>3. EMITTER, #1</p> <p>4. COLLECTOR, #1</p> <p>5. COLLECTOR, #2</p> <p>6. BASE, #2</p> <p>7. EMITTER, #2</p> <p>8. COLLECTOR, #2</p> <p>9. COLLECTOR, #3</p> <p>10. BASE, #3</p> <p>11. EMITTER, #3</p> <p>12. COLLECTOR, #3</p> <p>13. COLLECTOR, #4</p> <p>14. BASE, #4</p> <p>15. EMITTER, #4</p> <p>16. COLLECTOR, #4</p> | <p>STYLE 4:</p> <p>PIN 1. COLLECTOR, DYE #1</p> <p>2. COLLECTOR, #1</p> <p>3. COLLECTOR, #2</p> <p>4. COLLECTOR, #2</p> <p>5. COLLECTOR, #3</p> <p>6. COLLECTOR, #3</p> <p>7. COLLECTOR, #4</p> <p>8. COLLECTOR, #4</p> <p>9. BASE, #4</p> <p>10. EMITTER, #4</p> <p>11. BASE, #3</p> <p>12. EMITTER, #3</p> <p>13. BASE, #2</p> <p>14. EMITTER, #2</p> <p>15. BASE, #1</p> <p>16. EMITTER, #1</p> |
| <p>STYLE 5:</p> <p>PIN 1. DRAIN, DYE #1</p> <p>2. DRAIN, #1</p> <p>3. DRAIN, #2</p> <p>4. DRAIN, #2</p> <p>5. DRAIN, #3</p> <p>6. DRAIN, #3</p> <p>7. DRAIN, #4</p> <p>8. DRAIN, #4</p> <p>9. GATE, #4</p> <p>10. SOURCE, #4</p> <p>11. GATE, #3</p> <p>12. SOURCE, #3</p> <p>13. GATE, #2</p> <p>14. SOURCE, #2</p> <p>15. GATE, #1</p> <p>16. SOURCE, #1</p> | <p>STYLE 6:</p> <p>PIN 1. CATHODE</p> <p>2. CATHODE</p> <p>3. CATHODE</p> <p>4. CATHODE</p> <p>5. CATHODE</p> <p>6. CATHODE</p> <p>7. CATHODE</p> <p>8. CATHODE</p> <p>9. ANODE</p> <p>10. ANODE</p> <p>11. ANODE</p> <p>12. ANODE</p> <p>13. ANODE</p> <p>14. ANODE</p> <p>15. ANODE</p> <p>16. ANODE</p> | <p>STYLE 7:</p> <p>PIN 1. SOURCE N-CH</p> <p>2. COMMON DRAIN (OUTPUT)</p> <p>3. COMMON DRAIN (OUTPUT)</p> <p>4. GATE P-CH</p> <p>5. COMMON DRAIN (OUTPUT)</p> <p>6. COMMON DRAIN (OUTPUT)</p> <p>7. COMMON DRAIN (OUTPUT)</p> <p>8. SOURCE P-CH</p> <p>9. SOURCE P-CH</p> <p>10. COMMON DRAIN (OUTPUT)</p> <p>11. COMMON DRAIN (OUTPUT)</p> <p>12. COMMON DRAIN (OUTPUT)</p> <p>13. GATE N-CH</p> <p>14. COMMON DRAIN (OUTPUT)</p> <p>15. COMMON DRAIN (OUTPUT)</p> <p>16. SOURCE N-CH</p> | |

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MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

ON Semiconductor®



TSSOP-16
CASE 948F-01
ISSUE B

DATE 19 OCT 2006



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

| DIM | MILLIMETERS | | INCHES | |
|-----|-------------|------|-----------|-------|
| | MIN | MAX | MIN | MAX |
| A | 4.90 | 5.10 | 0.193 | 0.200 |
| B | 4.30 | 4.50 | 0.169 | 0.177 |
| C | --- | 1.20 | --- | 0.047 |
| D | 0.05 | 0.15 | 0.002 | 0.006 |
| F | 0.50 | 0.75 | 0.020 | 0.030 |
| G | 0.65 BSC | | 0.026 BSC | |
| H | 0.18 | 0.28 | 0.007 | 0.011 |
| J | 0.09 | 0.20 | 0.004 | 0.008 |
| J1 | 0.09 | 0.16 | 0.004 | 0.006 |
| K | 0.19 | 0.30 | 0.007 | 0.012 |
| K1 | 0.19 | 0.25 | 0.007 | 0.010 |
| L | 6.40 BSC | | 0.252 BSC | |
| M | 0° | 8° | 0° | 8° |

SOLDERING FOOTPRINT



GENERIC MARKING DIAGRAM*



- XXXX = Specific Device Code
- A = Assembly Location
- L = Wafer Lot
- Y = Year
- W = Work Week
- G or ■ = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present.

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